

Certificate

Standard **ISO 45001:2018**

Certificate Registr. No. **01 213 1930802**

Certificate Holder: **Micron Technology, Inc.**
Global EHS
Post office Box 6
8000 South Federal Way
Boise, Idaho 83707-0006
USA

including the locations according to annex

Scope: Design, Research and Development, Manufacture, Assembly and Test of Memory Components, Module and SSD Products

(Activities: Central Function - manages activities of the global multisite management system)

Proof has been furnished by means of an audit that the requirements of ISO 45001:2018 are met.

Validity: The certificate is valid from 2021-01-26 until 2024-01-25.
First certification 2021

2021-01-29



TÜV Rheinland Cert GmbH
Am Grauen Stein · 51105 Köln

Annex to certificate

Standard **ISO 45001:2018**

Certificate Registr. No. **01 213 1930802**

| No. | Location | Scope |
|-----|--|--|
| /01 | c/o Micron Technology, Inc. 8000 South Federal Way, Boise, ID 83707 USA | Design, Research and Development of Semiconductor Memory Components (Activities: Design, research and development, internal warehousing) |
| /02 | c/o Micron Technology, Inc. 9600 Godwin Drive Manassas VA 20110 USA | Manufacturing and Testing of Semiconductor Wafers [Activities: Wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, chemical vapor deposition, chemical mechanical planarization) and testing (probe)] |
| /04 | c/o Micron Semiconductor Asia Operations Pte. Ltd. 990 Bendemeer Road Singapore 339942 Singapore | Manufacturing and Testing of Memory Component, Module and SSD products for Semiconductors (Activities: Back-end manufacturing, wafer thinning, wafer saw, wire bond, encapsulation, burn-in, test operations, module and SSD assembly and package assembly, internal warehousing and logistics) |
| /05 | c/o Micron Semiconductor (Xi'an) Co., Ltd. Zone B, Shaanxi Xi'an Export, Processing Zone, Xin Xi Avenue, Xi'an Shaanxi Province, 710119 P.R. China | Manufacturing and Testing of Semiconductor Components and Module Products (Activities: Back-end manufacturing, test floor, burn-in, post electrical, module assembly and package assembly, die recovery, internal and external warehousing, logistics) |

Annex to certificate

Standard **ISO 45001:2018**

Certificate Registr. No. **01 213 1930802**

| | | |
|-----|--|---|
| /06 | c/o Micron Semiconductor Malaysia Sdn. Bhd. Tanjung Agas Industrial Area PO Box 62 84007 Muar, Johor Malaysia | Manufacturing and Testing of Semiconductor Components (Activities: Back-end manufacturing, wafer thinning, wafer saw, wire bond, encapsulation, test operations, die attach, post encapsulation, warehousing and logistics) |
| /07 | c/o Micron Semiconductor Asia Operations Pte. Ltd. 1 Woodlands Industrial Park D Singapore-Street 1 Singapore 738799 Singapore | Manufacturing and Testing of Semiconductor Components [Activities: Wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, thin film, chemical mechanical planarization), testing (probe) and internal warehousing] |
| /08 | c/o Micron Semiconductor Asia Operations Pte. Ltd. 1 Northcoast Drive Singapore 757432 Singapore | Research and Development, Manufacturing and Testing of Semiconductor Wafers [Activities: Design, research and development, wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, thin film, chemical mechanical planarization), testing (probe) and internal warehousing] |
| /09 | c/o Micron Memory Taiwan Co., Ltd. No. 369, Sec 4, Sanfong Road Houli District Central Taiwan Science Park Taichung City 42152 Taiwan, R.O.C. | Manufacturing and Testing of Semiconductor Wafers [Activities: Wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, chemical vapor deposition, chemical mechanical planarization and wafer probe testing), testing (probe) and internal warehousing] |

Annex to certificate

Standard **ISO 45001:2018**

Certificate Registr. No. **01 213 1930802**

- | | | |
|-----|---|---|
| /11 | c/o Micron Memory Japan, G.K. 7-10, Yoshikawa Kogyo Danchi, Higashi Hiroshima-shi Hiroshima-ken 739-0198 Japan | Research and Development, Manufacturing and Testing of Semiconductor Wafers [Activities: Research and development, wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, thin film, chemical mechanical planarization), testing (probe) and internal warehousing] |
| /12 | c/o Micron Memory Taiwan Co., Ltd. No. 667, Fuxing 3rd Road Hwa-Ya Technology Park Guishan District, Taoyuan City 333 Taiwan, R.O.C. | Manufacturing and Testing of Semiconductor Wafers [Activities: Wafer fabrication (diffusion, ion implantation, photolithography, wet process, dry etch, chemical vapor deposition, chemical mechanical planarization and wafer probe testing), testing (probe), internal and external warehousing] |
| /13 | c/o Micron Memory Taiwan Co., Ltd. No.88, No.88-1, Houke S. Rd. Houli Dist. Taichung City 42152 Taiwan, R.O.C. | Manufacturing and Testing of Semiconductor Module Products (Activities: Back-end manufacturing, wafer thinning, wafer saw, wire bond, encapsulation, burn-in, test operations, internal warehousing and logistics) |
| /15 | c/o Micron Memory Malaysia Sdn. Bhd. No. 1063, Plot 19 Tingkat Perusahaan 6, Prai Industrial Estate, 13600 Prai, Penang, Malaysia | Manufacturing and Testing of Semiconductor Module and SSD Products Activities: Back- end manufacturing, test operations, module and SSD assembly, internal warehousing and logistics |

Annex to certificate

Standard **ISO 45001:2018**

Certificate Registr. No. **01 213 1930802**

/17 c/o Micron Semiconductor Malaysia Sdn. Bhd.
K93 (PLO 74) Jalan Perindustrian 7
Tanjung Agas,
84007 Tangkak, Johor
Malaysia

Manufacturing and Testing of Semiconductor Components
(Activities: External warehousing, logistics)

2021-02-18


TÜV Rheinland Cert GmbH
Am Grauen Stein · 51105 Köln

Page 4 of 4